

SOT1065-1

plastic thin fine-pitch ball grid array package; 54 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA54
Package type industry code	TFBGA54
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	27-3-2008

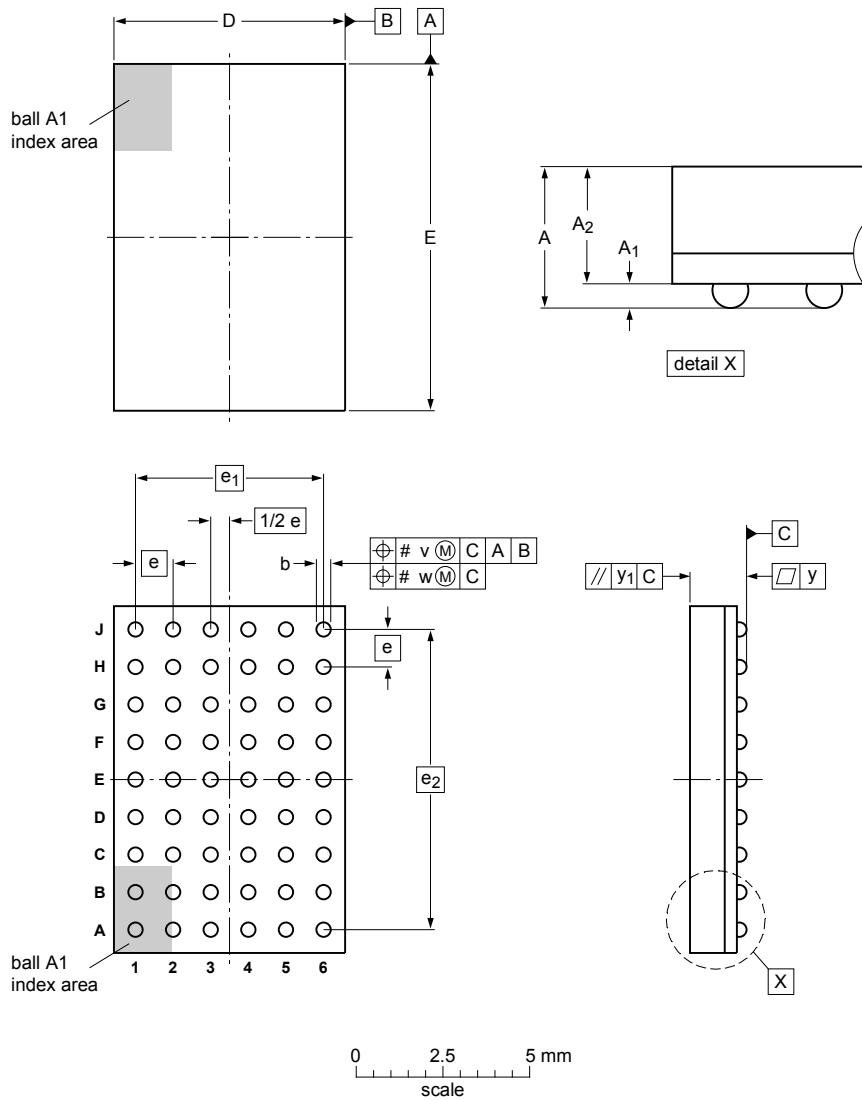
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	0.9	-	1	1.1	mm
A ₂	package height	0.75	-	0.8	0.85	mm
n ₂	actual quantity of termination	-	-	54	-	



2. Package outline

TFBGA54: plastic thin fine-pitch ball grid array package; 54 balls SOT1065-1



DIMENSIONS (mm are the original dimensions)

UNIT		A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	max	1.1	0.22	0.85	0.30	4.1	6.1	0.65	3.25	5.2	0.15	0.05	0.08	0.1
	nom	1.0	0.17	0.80	0.25	4.0	6.0							
	min	0.9	0.12	0.75	0.20	3.9	5.9							

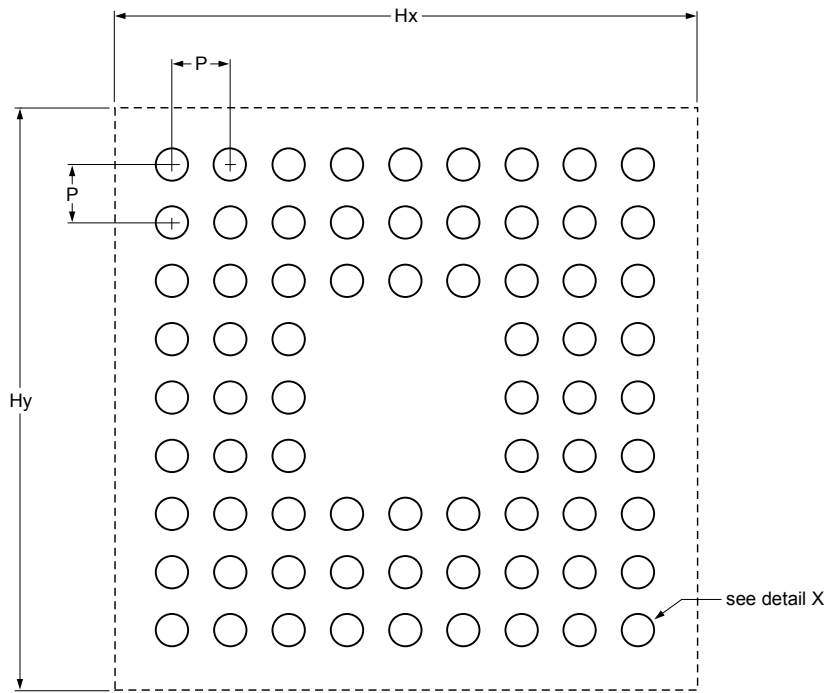
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1065-1	---	---	---			08-03-25 08-03-27

Fig. 1. Package outline TFBGA54 (SOT1065-1)




3. Soldering

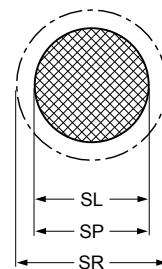
Footprint information for reflow soldering of TFBGA54 package

SOT1065-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.65	0.260	0.260	0.410	4.400	6.400

sot1065-1_fr

Fig. 2. Reflow soldering footprint for TFBGA54 (SOT1065-1)

4. Legal information

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